

PCN#: [IMO-AB-21-0074]

## **Product Change Notice (PCN)**

Subject: Add Back-End factories, materials, and change packing material of Tape & Reel for RX113 LQFP

package products

Publication Date: 12/24/2021 Effective Date: 4/1/2022

#### **Revision Description:**

Initial release.

#### **Description of Change:**

1)Add Back-End factories

1.1 Add the assembly factory

Current: Renesas Semiconductor (Beijing) Co., Ltd (RSB)

Addition: Greatek Electronics Inc., (Greatek)

1.2 Add the final test factory

Current: Renesas Semiconductor (Beijing) Co., Ltd (RSB)

Addition: King Yuan Electronics Co., Ltd. (KYEC)

#### 2)Add materials

When comparing with RSB products, there are some change as described below because of using the standard material and manufacturing equipment which are currently using in the Greatek factory.

#### 2.1 Material:

Lead frame, die mount and mold resin.

#### 2.2 Package outline and Marking on package:

Some differences for external dimensions. There is no change in footprint for Greatek products. Marking font.

### 2.3 Packing material:

Addition of bundling band color (Black)

#### 3) Change an emboss tape width:

Current: 32mm\* Addition: 24mm.

According to the change an emboss tape width, we also need to change cavity width, cavity depth, sprocket hole, dimension between center of sprocket hole and cavity, reel width and cover tape width.

\* The tape width of the current factory will also be planned to be changed to 24 mm.

## 4) Storage condition after opening

The storage conditions after opening the moisture proof bag of the Greatek product comply with JEDEC standards.

Current:  $30^{\circ}$  C /70%RH/within 168hr

Change: 30° C/60%RH/within 168hr(JEDEC compliant)

#### Affected Product List:

There are 6 part number of RX113 LQFP.

_	<b> </b>
	Ordering P/N
	R5F51135ADFP#1A
	R5F51136ADFP#1A
	R5F51135AGFP#1A
	R5F51136AGFP#1A
	R5F51135ADFP#5A
	R5F51136ADFP#5A

#### Reason for Change:

For Stable supply, we add Back-End factories.

#### Impact on Fit, Form, Function, Quality & Reliability:

Fit, Form: There are some changes in dimensions. Function, Quality and reliability: There are no impact.

#### **Product Identification:**

Possible to confirm the production history data from the packing label or trace code.

**Qualification Status:** Available by 1/31/2022. Contact Renesas sales, distributor, or agency.

Sample Availability Date: 4/1/2022

Device Material Declaration: Contact Renesas sales, distributor, or agency.



#### Note:

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# ADD BACK-END FACTORIES, MATERIALS AND CHANGE PACKING MATERIAL OF TAPE & REEL DIFFERENCE OF RX\_LQFP PRODUCTS

**Greatek Electronics Inc.,** 

King Yuan Electronics Co., Ltd

**DECEMBER 24, 2021** 

IOT PLATFORM BUSINESS DIVISION
IOT AND INFRASTRUCTURE BUSINESS UNIT
RENESAS ELECTRONICS CORPORATION

IMO-AB-21-0076



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(Rev. 5.0-1 October 2020)

## Content

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  - 2. Difference of specification's detail
  - 3. 4M changing points

## **Overview**

Thank you for continuously using our products.

For RX microcomputer products, we continuously add manufacturing factories and change assembly materials for stable supply.

For LQFP package products, manufacturing factories and assembly materials also are added this time.

Therefore, we would like to ask for your kind understanding and cooperation in order to make the procedure smoothly completed.

Yours sincerely,

Change points are reported in the following pages.

## 1. DIFFERENCE OF SPECIFICATION'S OUTLINE

Item		Current	Addition	Note
Assembly factory		Renesas Semiconductor (Beijing)	Group_Greatek Electronics Inc.	
Sorting factory		Co., Ltd	King Yuan Electronics Co., Ltd	-
	Lead frame	-	Change to standard material used in new factory. The structure not changed.	
Parts	Die mount	-	Change to standard material used in new factory. The structure not changed.	Refer to page 6
	Mould resin	-	Change to standard material used in new factory. The structure not changed.	
Package	Outline	-	There are changes in some of dimensions	Refer to page 7 to 10
Marking	Font	-	Font changed	Refer to page 11
	Bundling band color	-	Add black	-
Packing	Tape & Reel 14x14mm package	Embossed tape width 32 mm *	Embossed tape width 24 mm	Refer to page 12 to 13
Storage condition	After opening	Within 30°C/ 70%RH/ 168h	Within 30°C/ 60%RH/ 168h	_

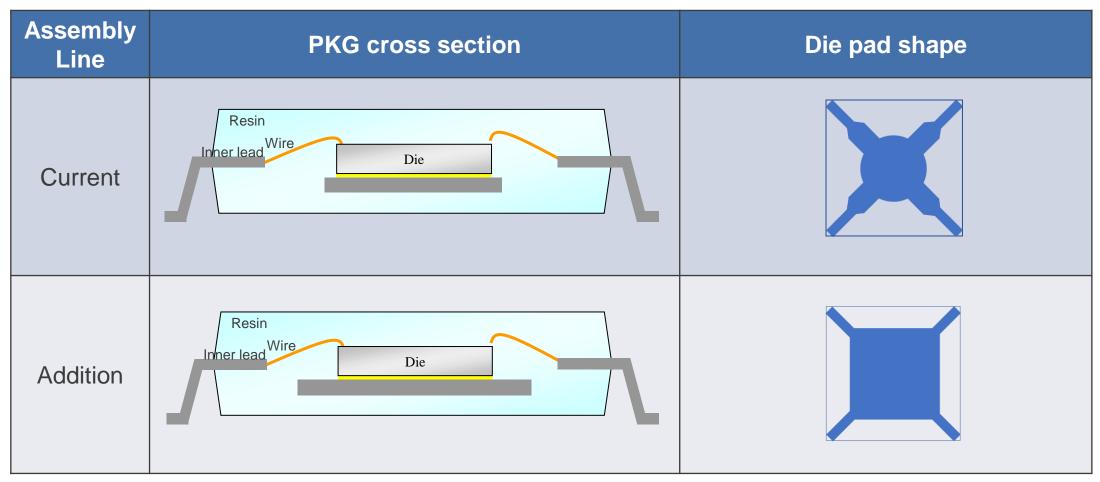
<sup>\*</sup>Current factory will also be planned to be changed to 24 mm.

<sup>\*</sup> There is no impact on reliability and specification

## 2. DIFFERENCE OF SPECIFICATION'S DETAIL (1)

## PACKAGE STRUCTURE(IMAGE)

\*PKG cross section and die pad shape are reference examples

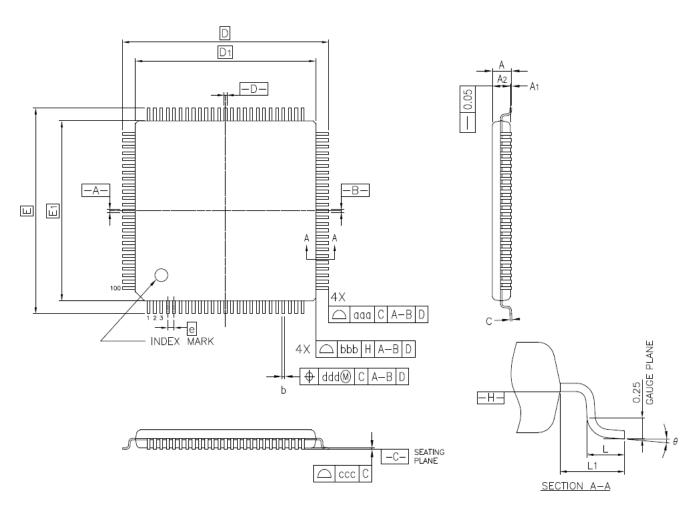


\* There is no impact on the reliability by die pad shape

## 2. DIFFERENCE OF SPECIFICATION'S DETAIL (2)

14x14mm 100pin LQFP package drawing (Addition)

RENESAS Code: PLQP0100KP-A

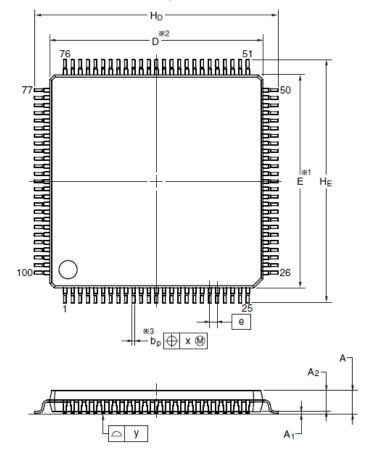


Reference	Dimension in Millimeters			
Symbol	Min.	Nom.	Max.	
А	_	_	1.60	
A <sub>1</sub>	0.05	_	0.15	
A <sub>2</sub>	1.35	1.40	1.45	
D	_	16.00	_	
D <sub>1</sub>	_	14.00	_	
Е	_	16.00	_	
E <sub>1</sub>	_	14.00	_	
N	_	100	_	
е	_	0.50	_	
b	0.17	0.22	0.27	
С	0.09	_	0.20	
θ	0,	3.5°	7°	
L	0.45	0.60	0.75	
L <sub>1</sub>	_	1.00	_	
aaa	_	_	0.20	
bbb	_	_	0.20	
ccc	_	_	0.08	
ddd	_	_	0.08	

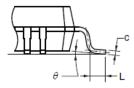
# 2. DIFFERENCE OF SPECIFICATION'S DETAIL (3)

14x14mm 100pin LQFP package drawing (Current)

RENESAS Code: PLQP0100KB-A



detail of lead end



- 1.Dimensions "%1" and "%2" do not include mold flash
- 2.Dimension "3" does not include trim offset.

Referance	Dimension in Millimeters			
Symbol	Min	Nom	Max	
D	13.90	14.00	14.10	
Е	13.90	14.00	14.10	
HD	15.80	16.00	16.20	
HE	15.80	16.00	16.20	
Α			1.70	
<b>A</b> <sub>1</sub>	0.05	0.10	0.15	
A2		1.40		
bp	0.15	0.20	0.25	
С	0.09	0.145	0.20	
L	0.35	0.50	0.65	
θ	<b>0</b> °		8°	
е		0.50		
х			0.08	
у			0.08	

## 2. DIFFERENCE OF SPECIFICATION'S DETAIL (4)

Dimension comparison: 14x14mm 100pin LQFP package

Greatek symbol is the same as the JEDEC standard.

Addition	14x14mm 100pin LQFP			Current	14x14r	nm 100pi	n LQFP
	PLQP0100KP-A				PLO	QP0100KE	3-A
Greatek	Dimens	ion in Mill	imeters	RSB	Dimens	ion in Mill	imeters
Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
А	-	-	1.60	Α	-	-	1.70
A1	0.05	-	0.15	A1	0.05	0.10	0.15
A2	1.35	1.40	1.45	A2	-	1.40	-
D	-	16.00	-	HD	15.80	16.00	16.20
D1	-	14.00	-	D	13.90	14.00	14.10
Е	-	16.00	-	HE	15.80	16.00	16.20
E1	-	14.00	-	Е	13.90	14.00	14.10
N	-	100	-	-	-	-	-
е	-	0.50	-	е	-	0.50	-
b	0.17	0.22	0.27	bp	0.15	0.20	0.25
С	0.09	-	0.20	С	0.09	0.145	0.20
θ	0°	3.5°	7°	θ	0°	-	8°
L *	0.45	0.60	0.75	Г	0.35	0.50	0.65
L1	-	1.00	-	L1	-	1.00	-
aaa	-	-	0.20	-	-	-	-
bbb	-	-	0.20	-	-	-	-
CCC	_	_	0.08	У	_	_	0.08
ddd	-	-	0.08	Х	-	-	0.08

<sup>\*</sup>The dimensions are equivalent to the current ones. The difference in the numerical value is because the part specified as the dimension is different.

## 2. DIFFERENCE OF SPECIFICATION'S DETAIL (5) Appearance:

14x14mm 100pin LQFP package

\*Marked character is reference example

		7. Markoa orialaotor le reference examp			
	Package surface	Package back	Worked Leads shape		
Current	R5F51136ADFP RX1136 029TZ00 3A				
Addition	R5F51136ADFP RX1136 134A907 3A WS				

<sup>\*</sup> There is no WS notation in the actual product

## 2. DIFFERENCE OF SPECIFICATION'S DETAIL (6)

## **Marking Font**

※Marked character is reference example

Assembly Line	Current	Addition
Whole Photo	R5F51136ADFP RX1136 029TZ00 3A	R5F51136ADFP RX1136 134A907 3A WS
Detail Photo		

<sup>\*</sup> There is no WS notation in the actual product

# 2. DIFFERENCE OF SPECIFICATION'S DETAIL (7)

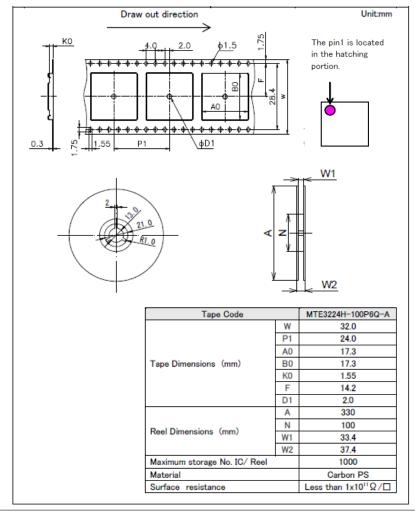
Comparison of tape & reel material details: 14x14mm 100pin LQFP package

Packing material	Item	Current	Addition
Emboss tape	Taping code	MTE3224H-100P6Q-A	E2424Q14RA
Emboss tape	Sprocket hole	Both side	One side
	Tape width	32mm	24mm
	Tape thickness	0.3mm	0.3mm
	Cavity size	17.3x17.3	16.5×16.5
	Cavity depth	1.55mm	1.4mm
	Distance between cavity centers	24mm	24mm
	Material	PS	PS
Reel	Reel diameter	330mm	330mm
Reel	Core diameter	100mm	100mm
	Reel width	32mm	24mm
Cover tape	Width	25.5mm	21.3mm

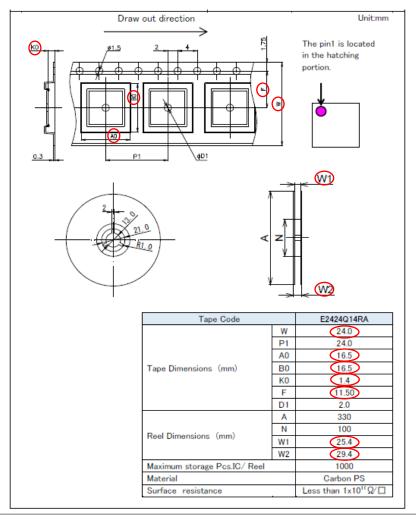
## 2. DIFFERENCE OF SPECIFICATION'S DETAIL (8)

Comparison of tape & reel dimension: 14mm x14mm x 1.4mm Tape & Reel





## Addition (W:24mm)



# 3. 4M changing points (Add the assembly factory and materials)

Item	Check result	Judgement
Machine	Changing at assembly. The machines are equivalent to present machines. There are production of similar copper wire products and we have already checked the additional products have no risk on the production.	No risk
Method	The same as current products.	No risk
Man	Adopt operator certification system. Only certificated operator can work for the production.	No risk
Material	Only use certificated materials. The products has been certificated by reliability test same as present products and have no risk.	No risk

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